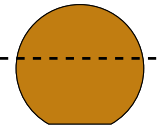


#1

Polished silicon wafer.



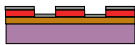
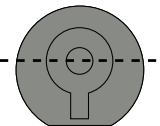
#2

Spin coating first layer of polyimide (5 μm).
Curing.



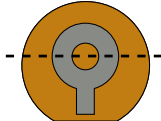
#3

Spin coating of negative resist (Ma-N 1420).



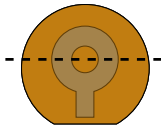
#4

Evaporation of Platinum (100 nm).



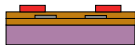
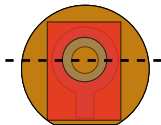
#5

Lift-off.



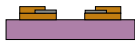
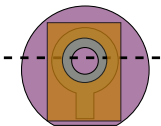
#6

Spin coating of second layer of polyimide (5 μm).



#7

Spin coating of positive resist (AZ 9260).



#8

Reactive Ion Etching of polyimide.
Release by peeling.